

PCN Number:	20190212001.0	PCN Date:	February 14, 2019
Title:	Datasheet for TMP302-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TMP302-Q1

SLOS889C – OCTOBER 2014 – REVISED SEPTEMBER 2018

Changes from Revision B (July 2015) to Revision C	Page
• Changed the supply voltage maximum value from: 3.6 V to: 4 V	4
• Changed the input pin supply voltage maximum value from: $V_S + 0.5 V$ to: $V_S + 0.3$ and $\leq 4 V$	4
• Changed the output pin voltage maximum value from: 3.6 V to: 4 V	4
• Added the specified temperature to the <i>Recommended Operating Conditions</i> table	4
• Updated junction-to-ambient thermal resistance from 200 to 210.3	4
• Updated junction-to-case (top) thermal resistance from 73.7 to 105.0	4
• Updated junction-to-board thermal resistance from 34.4 to 87.5	4
• Updated junction-to-top characterization parameter from 3.1 to 6.1	4
• Updated junction-to-board characterization parameter from 34.2 to 87.0	4
• Changed the <i>Design Requirements</i> section	10
• Added the <i>Receiving Notification of Documentation Updates</i> section	12

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP302-Q1	SLOS889B	SLOS889C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP302-Q1>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP302AQDRLRQ1	TMP302BQDRLRQ1	TMP302CQDRLRQ1	TMP302DQDRLRQ1
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For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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